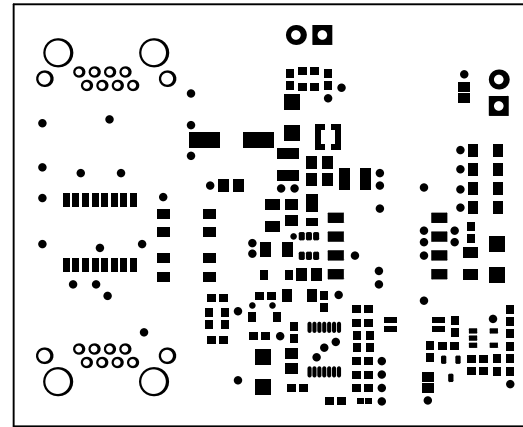
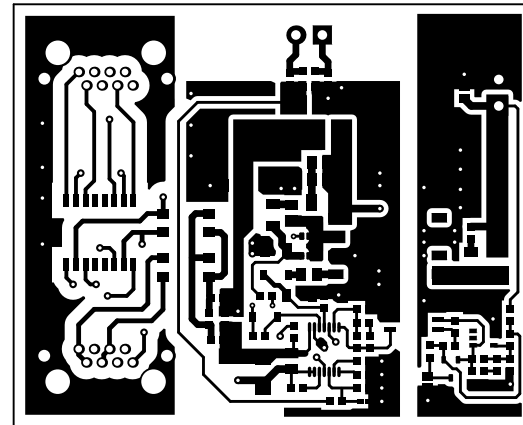


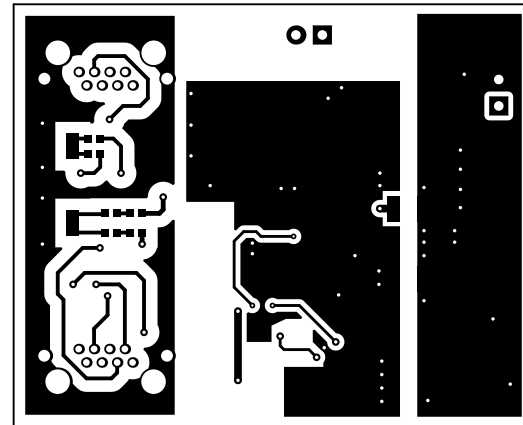
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 11/14/2016 4:53:26 PM	TEXAS INSTRUMENTS	



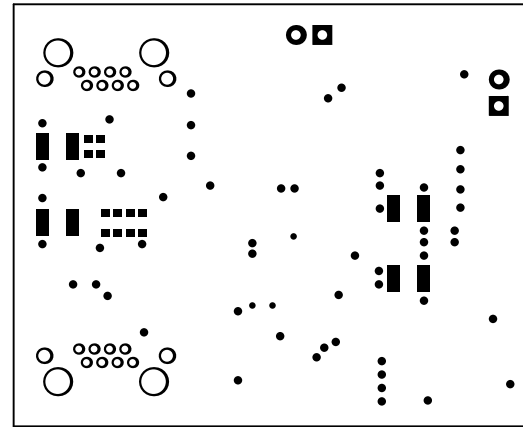
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 11/14/2016 4:53:26 PM	TEXAS INSTRUMENTS	



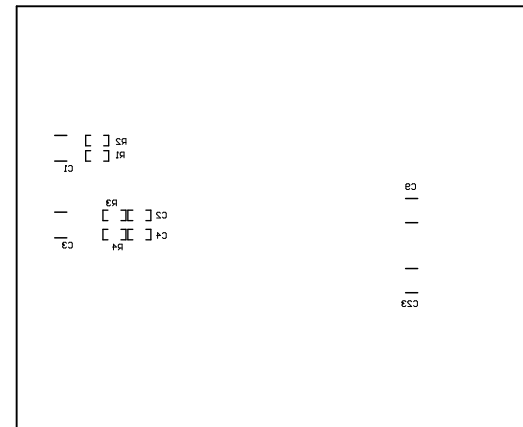
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 11/14/2016 4:53:27 PM	TEXAS INSTRUMENTS	



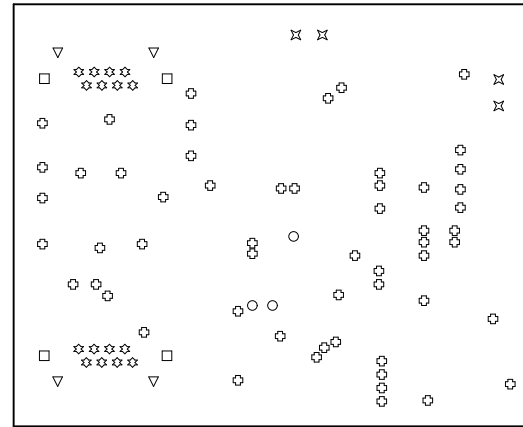
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 11/14/2016 4:53:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/14/2016 4:53:28 PM	TEXAS INSTRUMENTS	

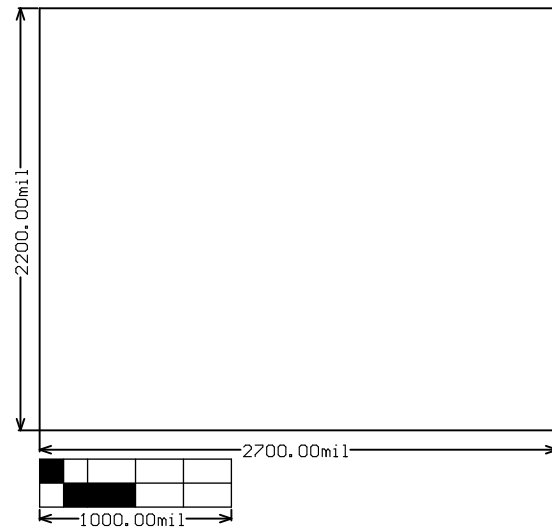


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 11/14/2016 4:53:28 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	3	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	56	18.00mil (0.457mm)	PTH	Round	Top Layer - Bottom Layer	
⊛*	16	35.04mil (0.890mm)	PTH	Round	Top Layer - Bottom Layer	
⊛X	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	61.81mil (1.570mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	128.00mil (3.251mm)	PTH	Round	Top Layer - Bottom Layer	
	87 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 11/14/2016 4:53:29 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20531	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 11/14/2016 4:53:29 PM	TEXAS INSTRUMENTS	

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